



General description

Symbol	Value
V_{DSS} @ $T_c=25^\circ\text{C}$	Min 650V
I_D @ $T_c=25^\circ\text{C}$	12.0A
$R_{DS(on)}$	Max 0.8Ω
Q_G	Typ 43nC

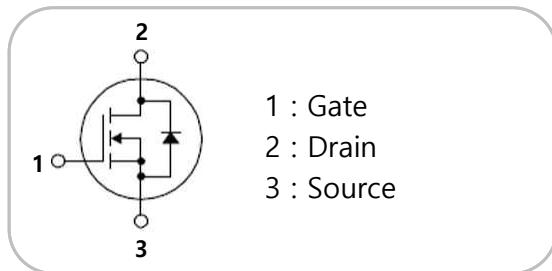


Package



Features

- Gate Charge(Typ. $Q_G=43\text{nC}$)
- High Voltage (Min. $V_{DSS}=650\text{V}$)
- 100% Avalanche Tested



Maximum Ratings ($T_c = 25^\circ\text{C}$)

Parameter	Symbol	Test Condition	Value	Units
Drain-source voltage	V_{DSS}	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	650	V
Drain current (DC)	I_D	$T_c=25^\circ\text{C}$	12.0	A
		$T_c=100^\circ\text{C}$	7.58	A
Drain current (Pulsed)	I_{DM}	Pulse width limited by junction temperature	48	A
Gate-source voltage	V_{GS}	-	± 30	V
Single pulsed avalanche energy	E_{AS}	$I_{AS}=12.0\text{A}$, $R_G=25\Omega$, $V_{DD}=50\text{V}$, $L=1.8\text{mH}$	140	mJ
Power dissipation	P_D	$T_c=25^\circ\text{C}$	45	W
Operating junction	T_j	-	-55 to 150	°C
Storage temperature	T_{stg}	-	-55 to 150	°C




Electrical Characteristics ($T_j = 25^\circ\text{C}$)

Parameter	Symbol	Test Condition				Units
			Min	Typ	Max	
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	650	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}}=650\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1.0	μA
Gate-source leakage current	I_{GSS}	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.0	-	4.0	V
Drain-source on-state resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=6.0\text{A}$	-	0.68	0.80	Ω
Input capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}$ $f = 1\text{MHz}$	-	2162	2882	pF
Output capacitance	C_{oss}		-	183	244	
Reverse transfer capacitance	C_{rss}		-	14.6	19.4	
Total gate charge	Q_{G}	$V_{\text{DS}}=520\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=12\text{A}$	-	43.0	65.0	nC
Gate-source charge	Q_{GS}		-	13.0	-	
Gate-drain charge	Q_{GD}		-	10.5	-	
Turn on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=300\text{V}, I_{\text{D}}=12\text{A}, R_{\text{G}}=25\Omega$	-	30	-	ns
Rise time	t_{r}		-	85	-	
Turn off delay time	$t_{\text{d}(\text{off})}$		-	140	-	
Fall time	t_{f}		-	90	-	



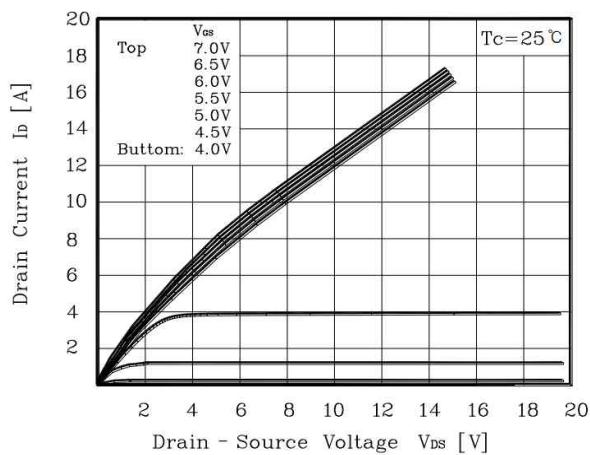
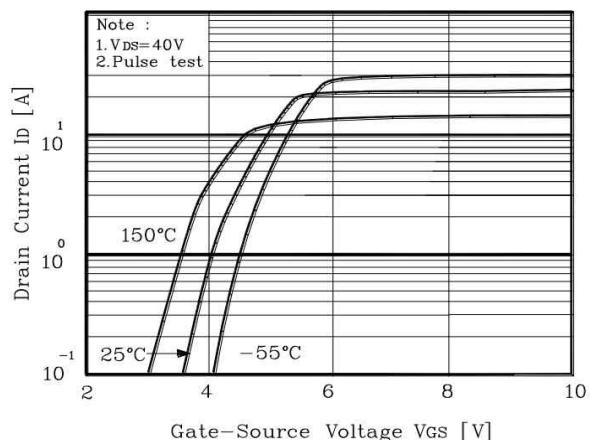
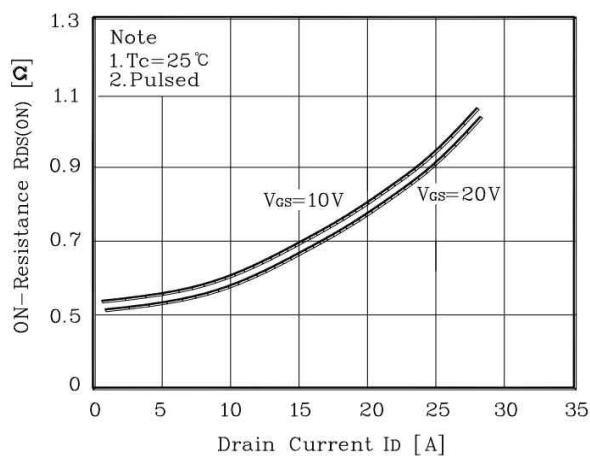
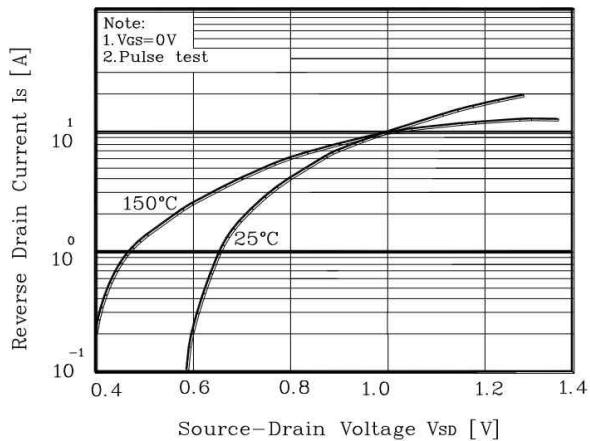
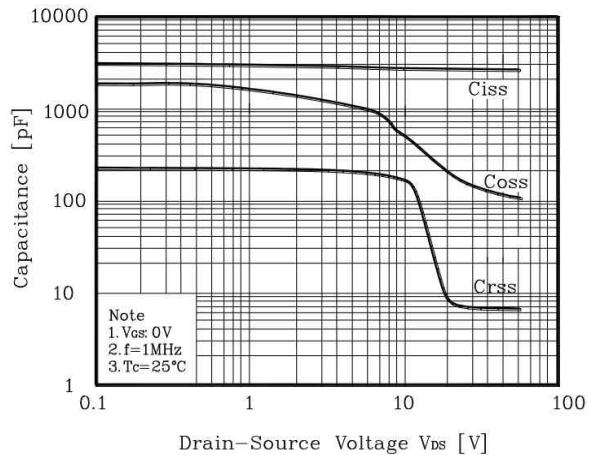
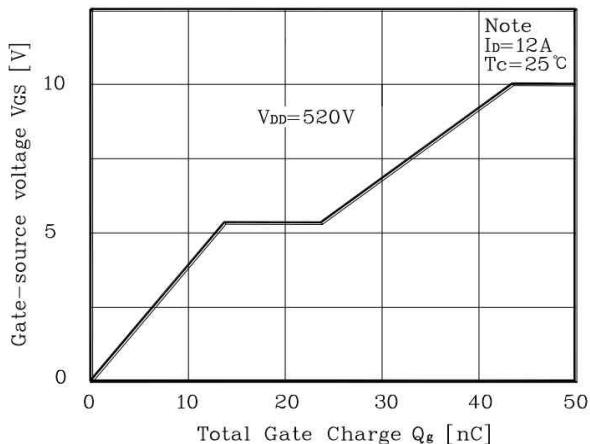

Body Diode(Source – Drain) Electrical Characteristics (T_j = 25°C)

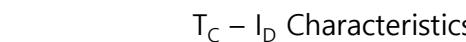
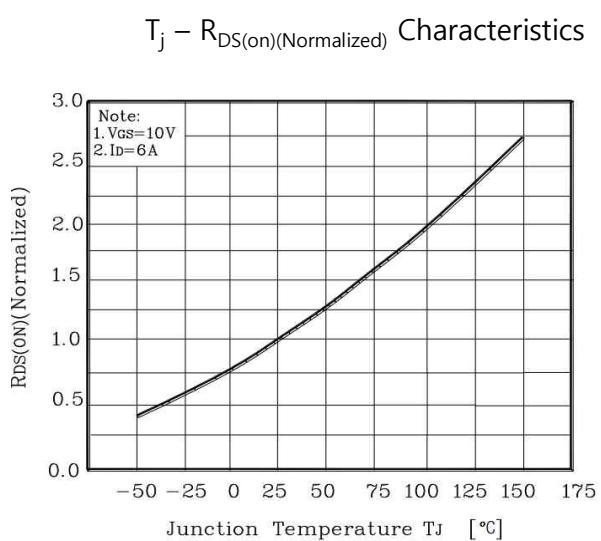
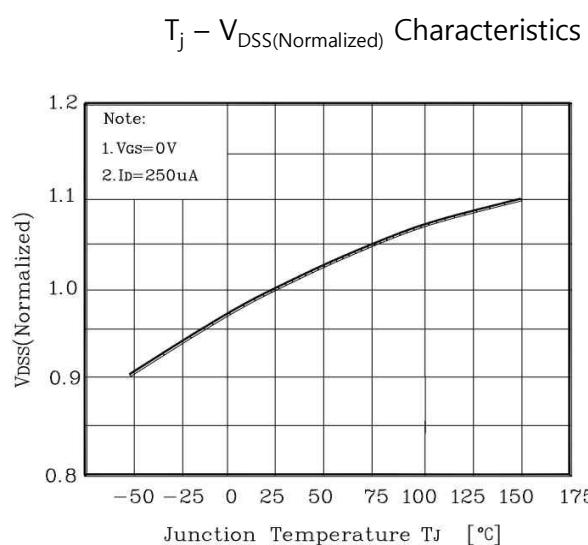
Parameter	Symbol	Test Condition	Value			Units
			Min	Typ	Max	
Continuous diode forward current	I _S	-	-	-	12.0	A
Maximum pulsed drain to source diode forward current	I _{SM}	-	-	-	48.0	A
Forward voltage	V _{SD}	I _{SD} =12A, V _{GS} =0V	-	-	1.4	V
Reverse recovery time	t _{rr}	I _{SD} =12A, V _{GS} =0V di/dt=100A/μs	-	500.0	-	ns
Reverse recovery charge	Q _{rr}		-	4.3	-	uC


Thermal Characteristics(T_C = 25°C)

Symbol	Parameter	Typ	Max	Units
R _{th(j-c)}	Junction to case	-	2.7	°C/W

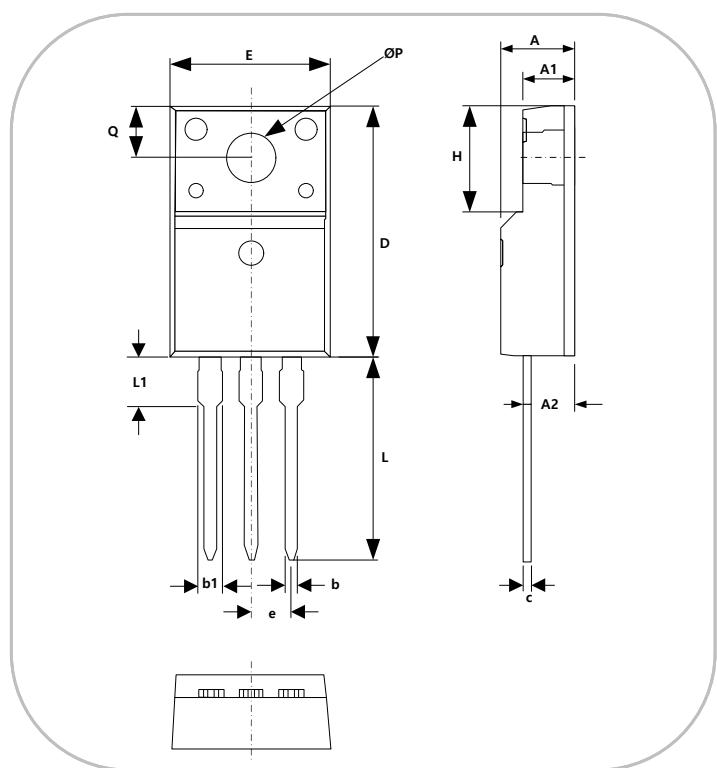


Typical Electrical Characteristics Curves ($T_j = 25^\circ\text{C}$) $V_{DS} - I_D$ Characteristics $V_{GS} - I_D$ Characteristics $I_D - R_{DS(on)}$ Characteristics $V_{SD} - I_S$ Characteristics $V_{DS} - C_T$ Characteristics $V_g - V_{GS}$ Characteristics


Typical Electrical Characteristics Curves ($T_j = 25^\circ\text{C}$)




Package Dimensions(TO-220F-3L)

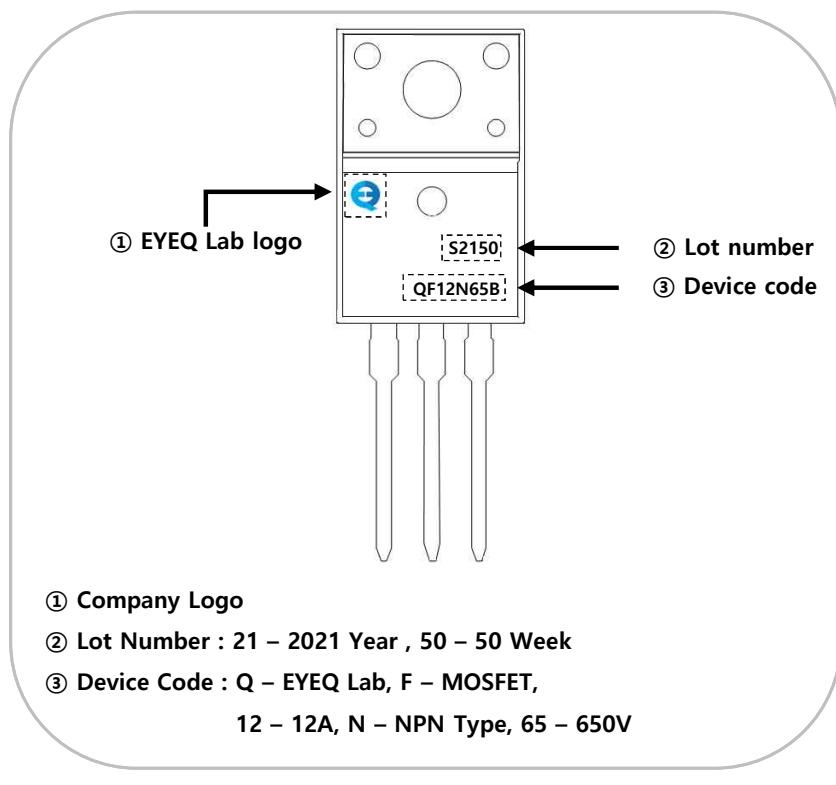


[Unit : mm]

SYMBOL	MIN	MAX
A	4.50	4.90
A1	2.34	2.74
A2	2.56	2.96
b	0.70	0.90
b1	1.27	1.47
c	0.45	0.60
D	15.67	16.07
E	9.96	10.36
e	2.54 BSC	
H	6.48	6.88
L	12.68	13.28
L1	3.03	3.43
φP	3.08	3.28
Q	3.20	3.40



Marking Information



① Company Logo

② Lot Number : 21 – 2021 Year , 50 – 50 Week

③ Device Code : Q – EYEQ Lab, F – MOSFET,

12 – 12A, N – NPN Type, 65 – 650V

